

Title (en)
HEAT TREATMENT METHOD FOR AMORPHOUS ALLOY RIBBON AND HEAT TREATMENT APPARATUS FOR AMORPHOUS ALLOY RIBBON

Title (de)
WÄRMEBEHANDLUNGSVERFAHREN FÜR AMORPHES LEGIERUNGSBAND UND WÄRMEBEHANDLUNGSVORRICHTUNG FÜR AMORPHES LEGIERUNGSBAND

Title (fr)
PROCÉDÉ DE TRAITEMENT THERMIQUE POUR RUBAN D'ALLIAGE AMORPHE ET APPAREIL DE TRAITEMENT THERMIQUE POUR RUBAN D'ALLIAGE AMORPHE

Publication
EP 4219774 A1 20230802 (EN)

Application
EP 21872499 A 20210922

Priority
• JP 2020160807 A 20200925
• JP 2021034822 W 20210922

Abstract (en)
The present invention provides a heat treatment method and a heat treatment apparatus for an amorphous alloy ribbon, said method and apparatus being capable of uniformly heat treating an amorphous alloy ribbon, while suppressing the occurrence of anisotropy in the magnetic characteristics. A heat treatment method for an amorphous alloy ribbon, said method comprising a step wherein an amorphous alloy ribbon is transferred, while being in contact with a heated projected surface, and the amorphous alloy ribbon is transferred, while having the part that is in contact with the projected surface pressed against the projected surface from a surface which is on the reverse side of the surface that is in contact with the projected surface.

IPC 8 full level
C21D 6/00 (2006.01); **H01F 1/153** (2006.01)

CPC (source: EP US)
C21D 1/26 (2013.01 - EP); **C21D 1/34** (2013.01 - EP); **C21D 9/0012** (2013.01 - US); **C21D 9/0068** (2013.01 - US); **C21D 9/563** (2013.01 - EP);
C21D 9/564 (2013.01 - EP); **C22C 1/11** (2023.01 - EP); **C22C 45/008** (2013.01 - US); **H01F 1/153** (2013.01 - EP); **H01F 1/15341** (2013.01 - US);
C21D 2201/03 (2013.01 - EP); **C22C 45/02** (2013.01 - EP); **C22C 2200/04** (2013.01 - US); **C22C 2202/02** (2013.01 - US)

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

Designated validation state (EPC)
KH MA MD TN

DOCDB simple family (publication)
EP 4219774 A1 20230802; CN 116261758 A 20230613; JP 7447381 B2 20240312; JP WO2022065370 A1 20220331;
US 2023366054 A1 20231116; WO 2022065370 A1 20220331

DOCDB simple family (application)
EP 21872499 A 20210922; CN 202180065276 A 20210922; JP 2021034822 W 20210922; JP 2022552035 A 20210922;
US 202118027924 A 20210922